L Number	Hits	Search Text	DB	Time stamp
1	106	soi and (vertical with interconnect) and field and (substrate with (etch$3 or remov$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 15:04
2	45	(soi and (vertical with interconnect) and field and (substrate with (etch$3 or remov$3))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 15:04
-	0	soi and ((via hole open$3 contact) with fox) and (thin$4 with backside with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 14:54
-	124	soi and (via hole open$3 contact) and (thin$4 with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:39
-	75	(soi and (via hole open$3 contact) and (thin$4 with substrate) and (backside with (connection or contact))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:41
-	69	soi and (via hole open$3 contact) and (backside with etch$3) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:54
-	41	(soi and (via hole open$3 contact) and (backside with etch$3) and (backside with (connection or contact))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:00
-	36	(form$3 with (via hole open$3 contact) with (field adj oxide)) and (backside with etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:58
-	25	((form$3 with (via hole open$3 contact) with (field adj oxide)) and (backside with etch$3)) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:23
-	2	5426072.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:23